

英飞凌 IMZA120R017M2H

CoolSiC™ 1200 V SiC MOSFET G2

采用 .XT 互连技术的碳化硅 MOSFET

特性

- $T_{vj} = 25^{\circ}\text{C}$ 时 $V_{DSS} = 1200\text{ V}$
- $I_{DDC} = 69\text{ A}$ 时 $T_C = 100^{\circ}\text{C}$
- $R_{DS(on)} = 17\text{ m}\Omega$ 时 $V_{GS} = 18\text{ V}$, $T_{vj} = 25^{\circ}\text{C}$
- 开关损耗非常低
- 过载运行最高结温可达 $T_{vj} = 200^{\circ}\text{C}$
- 短路耐受时间 $2\text{ }\mu\text{s}$
- 基准栅极阈值电压, $V_{GS(th)} = 4.2\text{ V}$
- 具有抗寄生导通能力, 可应用 0 V 关断栅极电压
- 坚固的体二极管, 适用于硬换向
- .XT 互连技术, 实现、行业领先的热性能
- 合适的英飞凌栅极驱动器可在 <https://www.infineon.com/gdfinder> 找到

潜在应用

- 通用驱动器 (GPD)
- 电动汽车充电桩
- 在线式UPS/工业UPS
- 组串式逆变器
- 储能系统(ESS)
- 焊接

产品验证

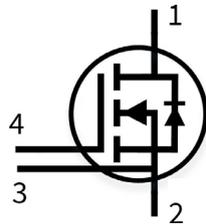
- 符合 JEDEC47/20/22 相关测试的工业应用要求

描述

引脚定义:

- 引脚 1 - 漏极
- 引脚 2 - 源
- 引脚 3 - 开尔文检测触点
- 引脚 4 - 栅极

注: 源极引脚和检测引脚不可互换, 互换可能会导致故障



Type	Package	Marking
IMZA120R017M2H	PG-TO247-4-U02	12M2H017

本数据手册的原文使用英文撰写。为方便起见, 英飞凌提供了译文; 由于翻译过程中可能使用了自动化工具, 英飞凌不保证译文的准确性。为确认准确性, 请务必访问 infineon.com 参考最新的英文版本 (控制文档)。

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1封装

1 封装

表1 特征值

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Storage temperature	T_{stg}		-55		150	°C
Soldering temperature	T_{sold}	Wave soldering 1.6 mm (0.063 in.) from case for 10 s			260	°C
Mounting torque	M	M3 screw, Maximum of mounting processes: 3			0.6	Nm
Thermal resistance, junction-ambient	$R_{th(j-a)}$				62	K/W
MOSFET/body diode thermal resistance, junction-case	$R_{th(j-c)}$			0.3	0.39	K/W

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表2 最大额定值

Parameter	Symbol	Note or test condition	Values	Unit	
Drain-source voltage	V_{DSS}	$T_{vj} \geq 25\text{ °C}$	1200	V	
Continuous DC drain current for $R_{th(j-c,max)}$, limited by $T_{vj(max)}$	I_{DCC}	$V_{GS} = 18\text{ V}$	$T_c = 25\text{ °C}$	97	A
			$T_c = 100\text{ °C}$	69	
Peak drain current, t_p limited by $T_{vj(max)}$ ¹⁾	I_{DM}	$V_{GS} = 18\text{ V}$	345	A	
Gate-source voltage, max. transient voltage	V_{GS}	$t_p \leq 0.5\ \mu\text{s}$, $D < 0.01$	-10...25	V	
Gate-source voltage, max. static voltage ²⁾	V_{GS}		-7...23	V	
Avalanche energy, single pulse	E_{AS}	$I_D = 40\text{ A}$, $V_{DD} = 50\text{ V}$, $L = 0.6\text{ mH}$, $T_{vj(start)} = 25\text{ °C}$	508	mJ	
Avalanche energy, repetitive	E_{AR}	$I_D = 40\text{ A}$, $V_{DD} = 50\text{ V}$, $L = 3.2\ \mu\text{H}$, $T_{vj(start)} = 25\text{ °C}$	2.54	mJ	
Short-circuit withstand time	t_{SC}	$V_{DD} \leq 800\text{ V}$, $V_{DS,peak} < 1200\text{ V}$, $V_{GS(on)} = 15\text{ V}$, $T_{vj(start)} = 25\text{ °C}$	2	μs	
Power dissipation, limited by $T_{vj(max)}$	P_{tot}		$T_c = 25\text{ °C}$	382	W
			$T_c = 100\text{ °C}$	191	

1) 已通过设计验证。

2) 应用设计中的最大栅源电压应符合IPC-9592B的规定。

表3 建议值

Parameter	Symbol	Note or test condition	Values	Unit
Recommended turn-on gate voltage	$V_{GS(on)}$		15...18	V
Recommended turn-off gate voltage	$V_{GS(off)}$		-5...0	V

表4 特征值

Parameter	Symbol	Note or test condition	Values			Unit	
			Min.	Typ.	Max.		
Drain-source on-state resistance	$R_{DS(on)}$	$I_D = 40\text{ A}$	$T_{vj} = 25\text{ °C}$, $V_{GS(on)} = 18\text{ V}$		17	23	mΩ
			$T_{vj} = 150\text{ °C}$, $V_{GS(on)} = 18\text{ V}$		35		
			$T_{vj} = 175\text{ °C}$, $V_{GS(on)} = 18\text{ V}$		41		
			$T_{vj} = 25\text{ °C}$, $V_{GS(on)} = 15\text{ V}$		21	29	
Gate-source threshold voltage	$V_{GS(th)}$	$I_D = 12.7\text{ mA}$, $V_{DS} = V_{GS}$ (tested after 1 ms pulse at $V_{GS} = 20\text{ V}$)	$T_{vj} = 25\text{ °C}$	3.5	4.2	5.1	V
			$T_{vj} = 175\text{ °C}$		3.2		
Zero gate-voltage drain current	I_{DSS}	$V_{DS} = 1200\text{ V}$, $V_{GS} = 0\text{ V}$	$T_{vj} = 25\text{ °C}$			350	μA
			$T_{vj} = 175\text{ °C}$		6		
Gate leakage current	I_{GSS}	$V_{DS} = 0\text{ V}$	$V_{GS} = 23\text{ V}$			120	nA
			$V_{GS} = -10\text{ V}$			-120	
Forward transconductance	g_{fs}	$I_D = 40\text{ A}$, $V_{DS} = 20\text{ V}$		27		S	
Internal gate resistance	$R_{G,int}$	$f = 1\text{ MHz}$, $V_{AC} = 25\text{ mV}$		3		Ω	
Input capacitance	C_{iss}	$V_{DS} = 800\text{ V}$, $V_{GS} = 0\text{ V}$, $f = 100\text{ kHz}$, $V_{AC} = 25\text{ mV}$		2910		pF	
Output capacitance	C_{oss}	$V_{DS} = 800\text{ V}$, $V_{GS} = 0\text{ V}$, $f = 100\text{ kHz}$, $V_{AC} = 25\text{ mV}$		126		pF	
Reverse transfer capacitance	C_{rss}	$V_{DS} = 800\text{ V}$, $V_{GS} = 0\text{ V}$, $f = 100\text{ kHz}$, $V_{AC} = 25\text{ mV}$		11		pF	
C_{oss} stored energy	E_{oss}	Calculated based on $C_{oss} = f(V_{DD})$		53		μJ	
Output charge	Q_{oss}	Calculated based on $C_{oss} = f(V_{DD})$		196		nC	
Effective output capacitance, energy related	$C_{o(er)}$	$V_{DS} = 0...800\text{ V}$, $V_{GS} = 0\text{ V}$, Calculated based on E_{oss}		166		pF	
Effective output capacitance, time related	$C_{o(tr)}$	$I_D = \text{constant}$, $V_{DS} = 0...800\text{ V}$, $V_{GS} = 0\text{ V}$, Calculated based on Q_{oss}		245		pF	
Total gate charge	Q_G	$V_{DD} = 800\text{ V}$, $I_D = 40\text{ A}$, $V_{GS} = 0/18\text{ V}$, turn-on pulse		89		nC	

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表 4 (续) 特征值

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Plateau gate charge	$Q_{GS(pl)}$	$V_{DD} = 800\text{ V}$, $I_D = 40\text{ A}$, $V_{GS} = 0/18\text{ V}$, turn-on pulse		19		nC
Gate-drain charge	Q_{GD}	$V_{DD} = 800\text{ V}$, $I_D = 40\text{ A}$, $V_{GS} = 0/18\text{ V}$, turn-on pulse		24		nC
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 800\text{ V}$, $I_D = 40\text{ A}$, $V_{GS} = 0/18\text{ V}$, $R_{G,ext} = 2.3\ \Omega$, $L_\sigma = 12\text{ nH}$, diode: body diode at $V_{GS} = 0\text{ V}$	$T_{vj} = 25\text{ }^\circ\text{C}$	10		ns
			$T_{vj} = 175\text{ }^\circ\text{C}$	7.5		
Rise time	t_r	$V_{DD} = 800\text{ V}$, $I_D = 40\text{ A}$, $V_{GS} = 0/18\text{ V}$, $R_{G,ext} = 2.3\ \Omega$, $L_\sigma = 12\text{ nH}$, diode: body diode at $V_{GS} = 0\text{ V}$	$T_{vj} = 25\text{ }^\circ\text{C}$	6.1		ns
			$T_{vj} = 175\text{ }^\circ\text{C}$	5.4		
Turn-off delay time	$t_{d(off)}$	$V_{DD} = 800\text{ V}$, $I_D = 40\text{ A}$, $V_{GS} = 0/18\text{ V}$, $R_{G,ext} = 2.3\ \Omega$, $L_\sigma = 12\text{ nH}$, diode: body diode at $V_{GS} = 0\text{ V}$	$T_{vj} = 25\text{ }^\circ\text{C}$	21.2		ns
			$T_{vj} = 175\text{ }^\circ\text{C}$	24.8		
Fall time	t_f	$V_{DD} = 800\text{ V}$, $I_D = 40\text{ A}$, $V_{GS} = 0/18\text{ V}$, $R_{G,ext} = 2.3\ \Omega$, $L_\sigma = 12\text{ nH}$, diode: body diode at $V_{GS} = 0\text{ V}$	$T_{vj} = 25\text{ }^\circ\text{C}$	9.1		ns
			$T_{vj} = 175\text{ }^\circ\text{C}$	10.7		
Turn-on energy	E_{on}	$V_{DD} = 800\text{ V}$, $I_D = 40\text{ A}$, $V_{GS} = 0/18\text{ V}$, $R_{G,ext} = 2.3\ \Omega$, $L_\sigma = 12\text{ nH}$, diode: body diode at $V_{GS} = 0\text{ V}$	$T_{vj} = 25\text{ }^\circ\text{C}$	310		μJ
			$T_{vj} = 175\text{ }^\circ\text{C}$	550		
Turn-off energy	E_{off}	$V_{DD} = 800\text{ V}$, $I_D = 40\text{ A}$, $V_{GS} = 0/18\text{ V}$, $R_{G,ext} = 2.3\ \Omega$, $L_\sigma = 12\text{ nH}$, diode: body diode at $V_{GS} = 0\text{ V}$	$T_{vj} = 25\text{ }^\circ\text{C}$	120		μJ
			$T_{vj} = 175\text{ }^\circ\text{C}$	180		
Total switching energy ¹⁾	E_{tot}	$V_{DD} = 800\text{ V}$, $I_D = 40\text{ A}$, $V_{GS} = 0/18\text{ V}$, $R_{G,ext} = 2.3\ \Omega$, $L_\sigma = 12\text{ nH}$, diode: body diode at $V_{GS} = 0\text{ V}$	$T_{vj} = 25\text{ }^\circ\text{C}$	590		μJ
			$T_{vj} = 175\text{ }^\circ\text{C}$	1200		

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表 4 (续) 特征值

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Turn-on energy at -5 V	E_{on}	$V_{DD} = 800\text{ V}$, $I_D = 40\text{ A}$, $V_{GS} = -5/18\text{ V}$, $R_{G,ext} = 2.3\ \Omega$, $L_\sigma = 12\text{ nH}$, diode: body diode at $V_{GS} = -5\text{ V}$	$T_{vj} = 25\text{ }^\circ\text{C}$	288		μJ
			$T_{vj} = 175\text{ }^\circ\text{C}$	513		
Turn-off energy at -5 V	E_{off}	$V_{DD} = 800\text{ V}$, $I_D = 40\text{ A}$, $V_{GS} = -5/18\text{ V}$, $R_{G,ext} = 2.3\ \Omega$, $L_\sigma = 12\text{ nH}$, diode: body diode at $V_{GS} = -5\text{ V}$	$T_{vj} = 25\text{ }^\circ\text{C}$	53		μJ
			$T_{vj} = 175\text{ }^\circ\text{C}$	53		
Total switching energy at -5 V ¹⁾	E_{tot}	$V_{DD} = 800\text{ V}$, $I_D = 40\text{ A}$, $V_{GS} = -5/18\text{ V}$, $R_{G,ext} = 2.3\ \Omega$, $L_\sigma = 12\text{ nH}$, diode: body diode at $V_{GS} = -5\text{ V}$	$T_{vj} = 25\text{ }^\circ\text{C}$	506		μJ
			$T_{vj} = 175\text{ }^\circ\text{C}$	1122		
Virtual junction temperature	T_{vj}		-55		175	$^\circ\text{C}$
Virtual junction temperature	$T_{vj(over)}$	overload, cumulative max. 100 h ²⁾			200	$^\circ\text{C}$

1) 包括 E_{fr}

2) 最多 5000 次循环。最大 ΔT 限制为 100 K。

注：芯片技术的特征是高达 200 kV/ μs 。测量的 dV/dt 受到测量测试设置和封装的限制。

除非另有规定，特性均为 $T_{vj} = 25\text{ }^\circ\text{C}$ 。

3 体二极管 (MOSFET)

表5 最大额定值

Parameter	Symbol	Note or test condition	Values	Unit	
Drain-source voltage	V_{DSS}	$T_{vj} \geq 25\text{ }^\circ\text{C}$	1200	V	
Continuous reverse drain current for $R_{th(j-c,max)}$, limited by $T_{vj(max)}$	I_{SDC}	$V_{GS} = 0\text{ V}$	$T_c = 25\text{ }^\circ\text{C}$	72	A
			$T_c = 100\text{ }^\circ\text{C}$	40	
Peak reverse drain current, t_p limited by $T_{vj(max)}$	I_{SM}	$V_{GS} = 0\text{ V}$	207	A	

表6 特征值

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Drain-source reverse voltage	V_{SD}	$I_{SD} = 40 \text{ A}, V_{GS} = 0 \text{ V}$	$T_{vj} = 25 \text{ }^\circ\text{C}$	4.2	5.5	V
			$T_{vj} = 100 \text{ }^\circ\text{C}$	4.11		
			$T_{vj} = 175 \text{ }^\circ\text{C}$	4.05		
MOSFET forward recovery charge	Q_{fr}	$V_{DD} = 800 \text{ V}, I_{SD} = 40 \text{ A}, V_{GS} = 0 \text{ V}, R_{GS(on)} = 2.3 \text{ } \Omega, Q_{fr}$ includes also Q_C	$T_{vj} = 25 \text{ }^\circ\text{C}$	0.34		μC
			$T_{vj} = 175 \text{ }^\circ\text{C}$	0.97		
MOSFET peak forward recovery current	I_{frm}	$V_{DD} = 800 \text{ V}, I_{SD} = 40 \text{ A}, V_{GS} = 0 \text{ V}, R_{GS(on)} = 2.3 \text{ } \Omega, Q_{fr}$ includes also Q_C	$T_{vj} = 25 \text{ }^\circ\text{C}$	41.7		A
			$T_{vj} = 175 \text{ }^\circ\text{C}$	71.2		
MOSFET forward recovery energy	E_{fr}	$V_{DD} = 800 \text{ V}, I_{SD} = 40 \text{ A}, V_{GS} = 0 \text{ V}, R_{GS(on)} = 2.3 \text{ } \Omega, Q_{fr}$ includes also Q_C	$T_{vj} = 25 \text{ }^\circ\text{C}$	160		μJ
			$T_{vj} = 175 \text{ }^\circ\text{C}$	470		
MOSFET forward recovery energy at -5 V	E_{fr}	$V_{DD} = 800 \text{ V}, I_{SD} = 40 \text{ A}, V_{GS} = -5 \text{ V}, R_{GS(on)} = 2.3 \text{ } \Omega, Q_{fr}$ includes also Q_C	$T_{vj} = 25 \text{ }^\circ\text{C}$	165		μJ
			$T_{vj} = 175 \text{ }^\circ\text{C}$	556		
Virtual junction temperature	T_{vj}		-55		175	$^\circ\text{C}$
Virtual junction temperature	$T_{vj(over)}$	overload, cumulative max. 100 h ¹⁾			200	$^\circ\text{C}$

1) 最多 5000 次循环。最大 ΔT 限制为 100 K。

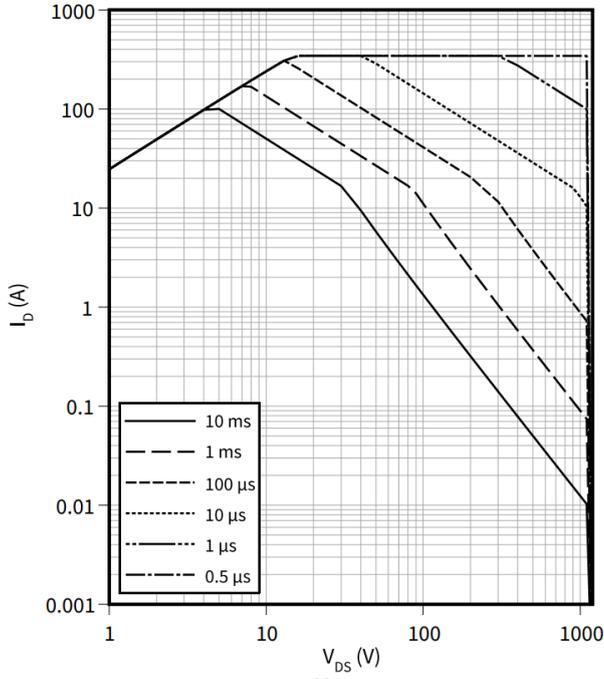
4 特性图

4 特性图

Safe operating area (SOA)

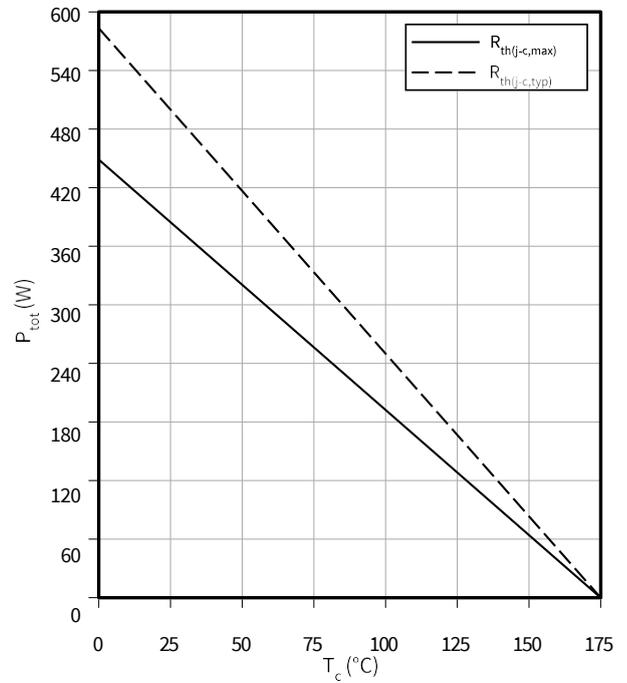
$I_D = f(V_{DS})$

$T_{vj} \leq 175^\circ\text{C}, T_c = 25^\circ\text{C}$



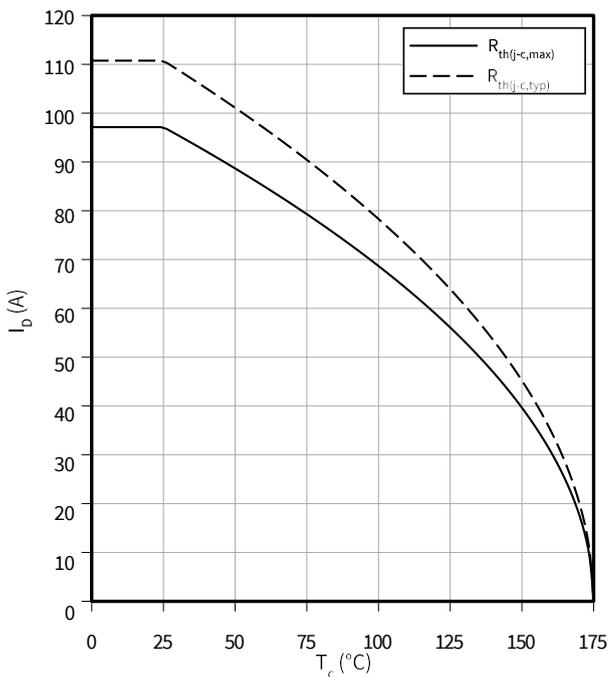
Power dissipation as a function of case temperature

$P_{tot} = f(T_c)$



Maximum DC drain to source current as a function of case temperature limited by bond wire

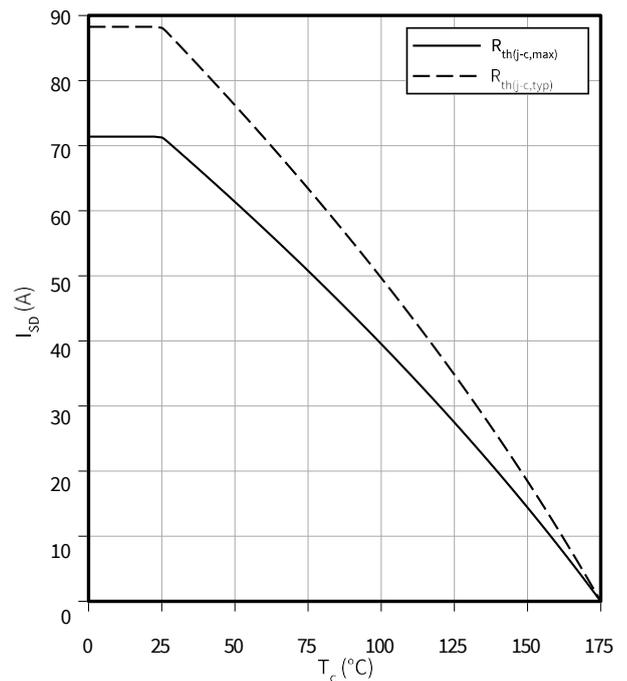
$I_D = f(T_c)$



Maximum source to drain current as a function of case temperature limited by bond wire

$I_{SD} = f(T_c)$

$V_{GS} = 0\text{ V}$

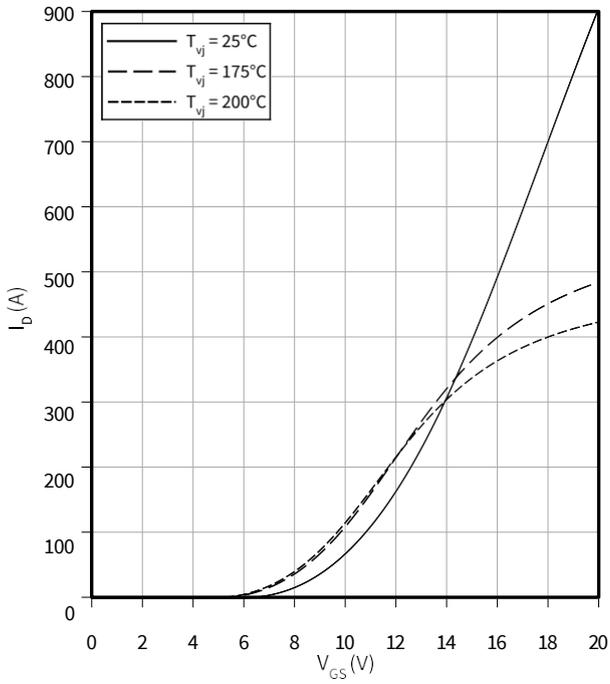


4 特性图

Typical transfer characteristic

$I_D = f(V_{GS})$

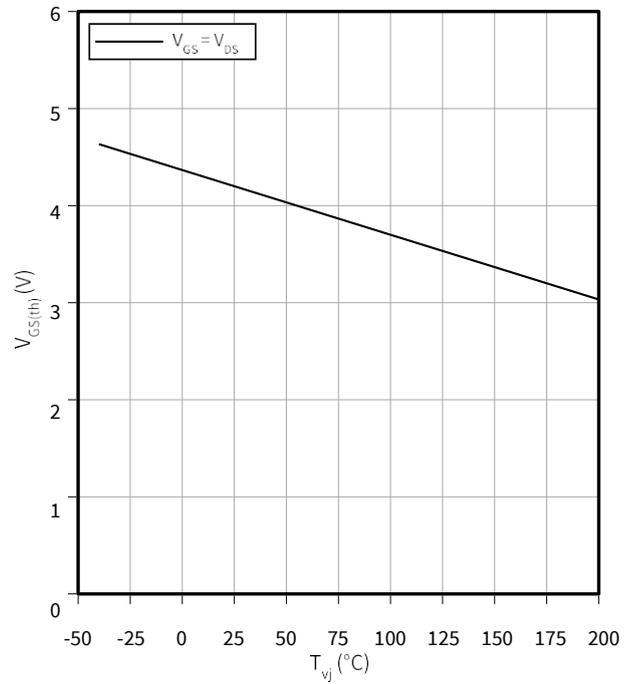
$V_{DS} = 20 \text{ V}$, $t_p = 20 \mu\text{s}$



Typical gate-source threshold voltage as a function of junction temperature

$V_{GS(th)} = f(T_{vj})$

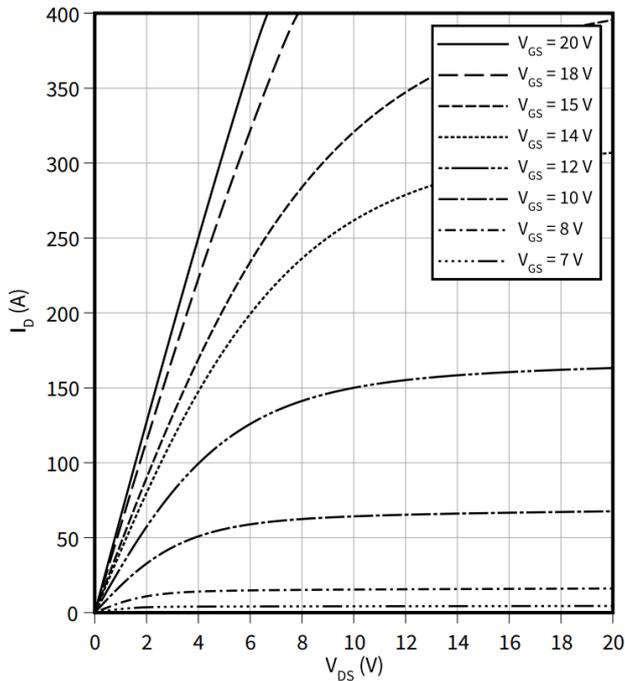
$I_D = 12.7 \text{ mA}$



Typical output characteristic, V_{GS} as a parameter

$I_D = f(V_{DS})$

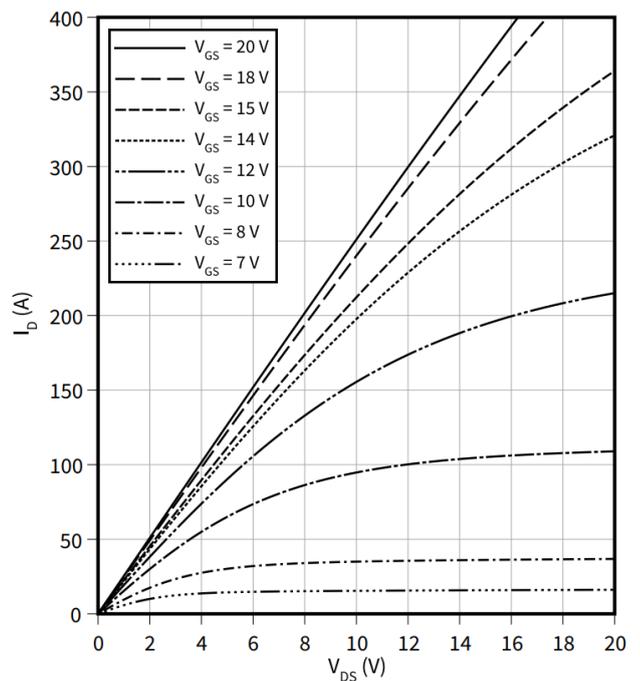
$T_{vj} = 25^\circ\text{C}$, $t_p = 20 \mu\text{s}$



Typical output characteristic, V_{GS} as a parameter

$I_D = f(V_{DS})$

$T_{vj} = 175^\circ\text{C}$, $t_p = 20 \mu\text{s}$

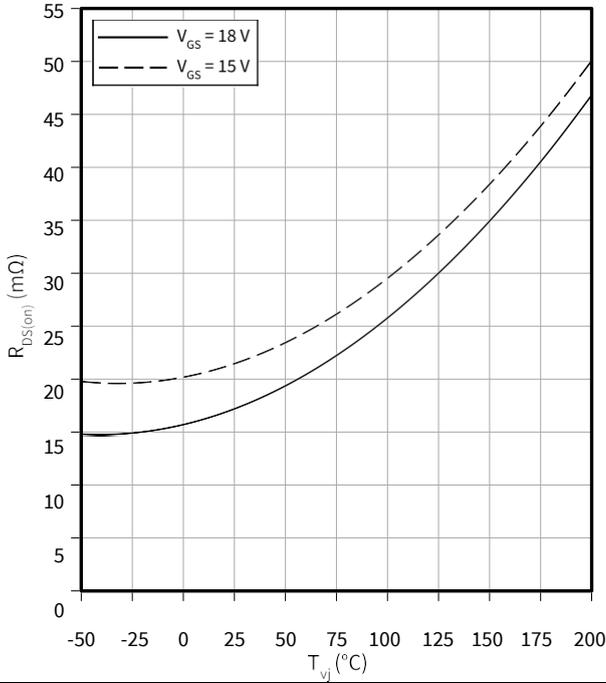


4 特性图

Typical on-state resistance as a function of junction temperature

$R_{DS(on)} = f(T_{vj})$

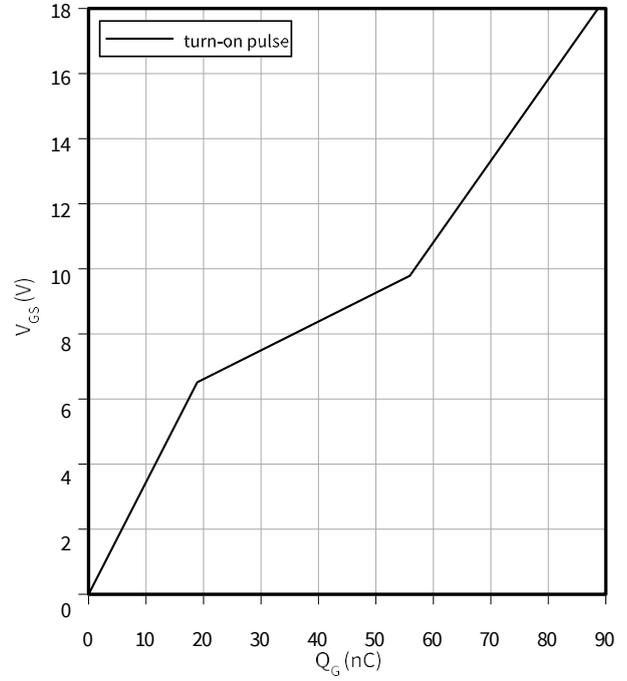
$I_D = 40\text{ A}$



Typical gate charge

$V_{GS} = f(Q_G)$

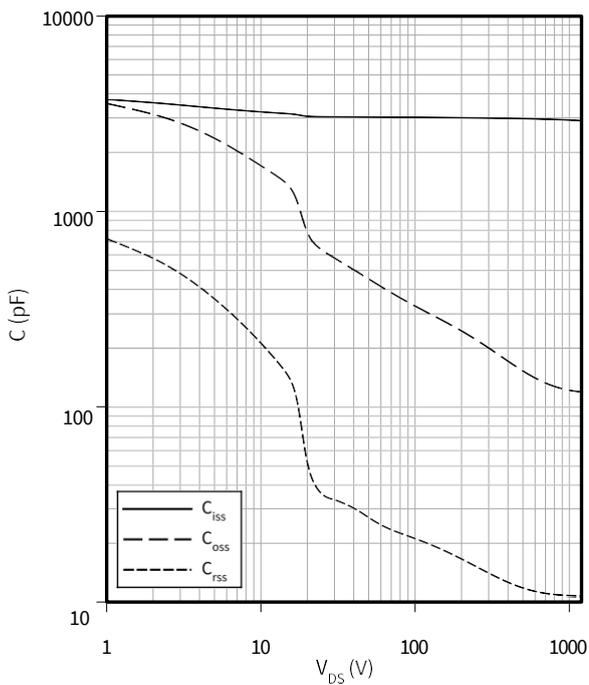
$I_D = 40\text{ A}, V_{DS} = 800\text{ V}$



Typical capacitance as a function of drain-source voltage

$C = f(V_{DS})$

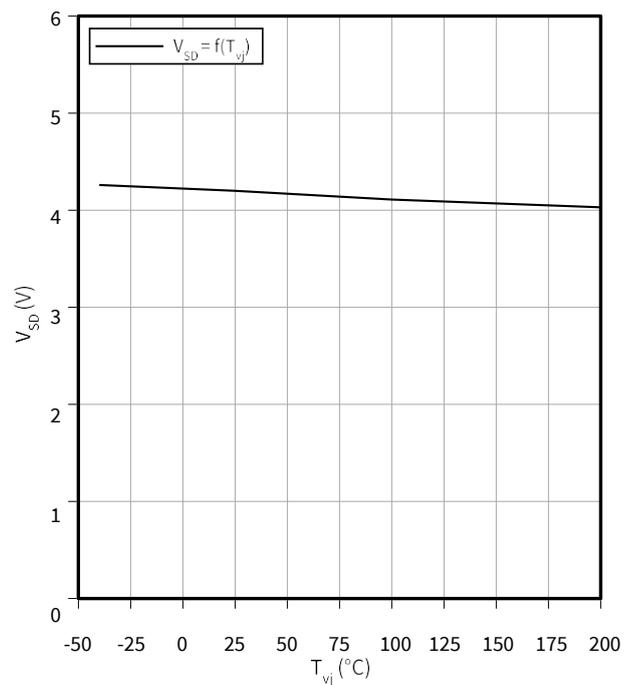
$f = 100\text{ kHz}, V_{GS} = 0\text{ V}$



Typical reverse drain voltage as a function of junction temperature

$V_{SD} = f(T_{vj})$

$I_{SD} = 40\text{ A}, V_{GS} = 0\text{ V}$

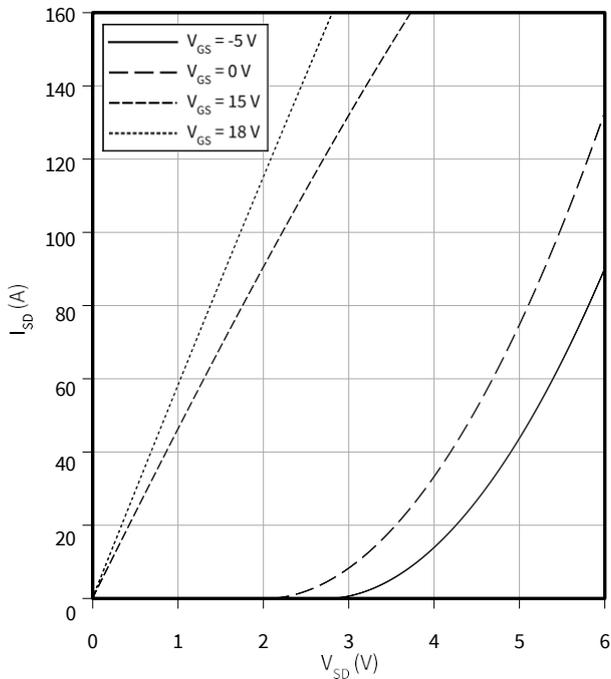


4 特性图

Typical reverse drain current as a function of reverse drain voltage, V_{GS} as a parameter

$I_{SD} = f(V_{SD})$

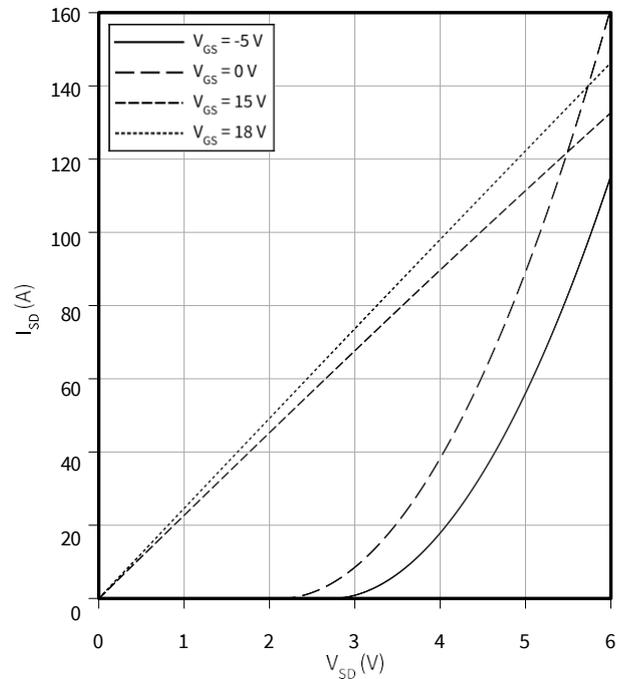
$T_{vj} = 25\text{ °C}$, $t_p = 20\ \mu\text{s}$



Typical reverse drain current as a function of reverse drain voltage, V_{GS} as a parameter

$I_{SD} = f(V_{SD})$

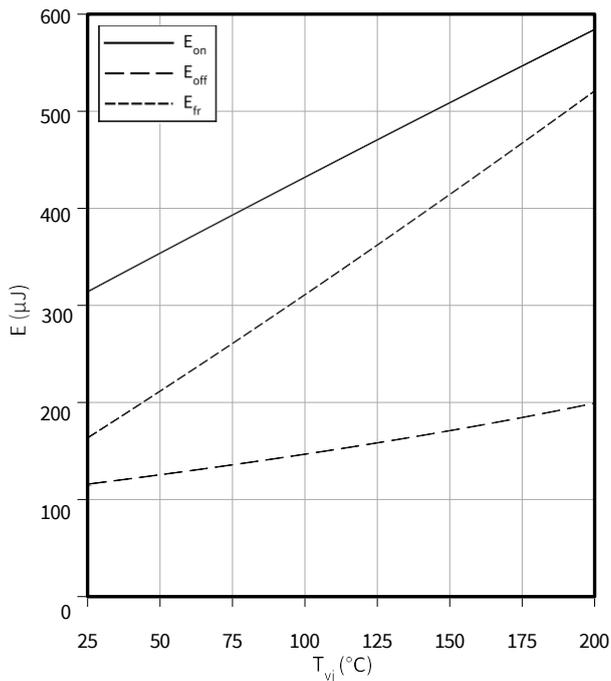
$T_{vj} = 175\text{ °C}$, $t_p = 20\ \mu\text{s}$



Typical switching energy as a function of junction temperature, test circuit in Fig. F, 2nd device own body diode: $V_{GS} = 0\text{ V}$

$E = f(T_{vj})$

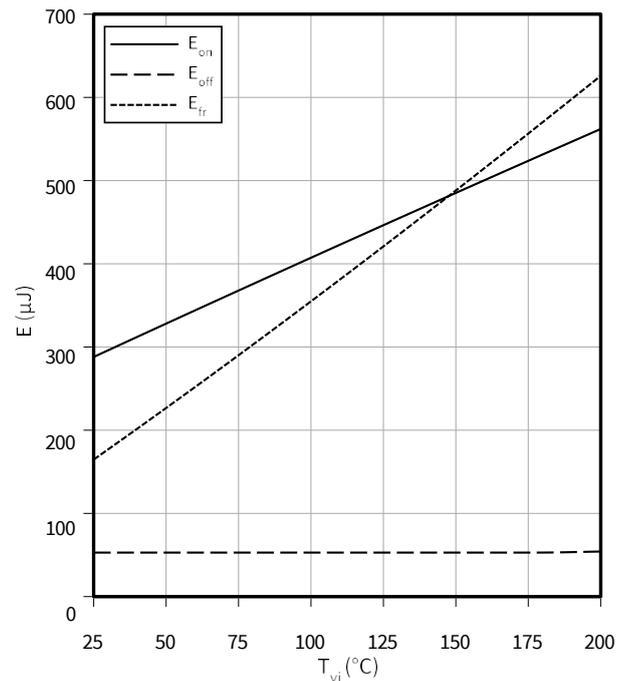
$V_{GS} = 0/18\text{ V}$, $I_D = 40\text{ A}$, $R_{G,ext} = 2.3\ \Omega$, $V_{DD} = 800\text{ V}$



Typical switching energy as a function of junction temperature, test circuit in Fig. F, 2nd device own body diode: $V_{GS} = -5\text{ V}$

$E = f(T_{vj})$

$V_{GS} = -5/18\text{ V}$, $I_D = 40\text{ A}$, $R_{G,ext} = 2.3\ \Omega$, $V_{DD} = 800\text{ V}$

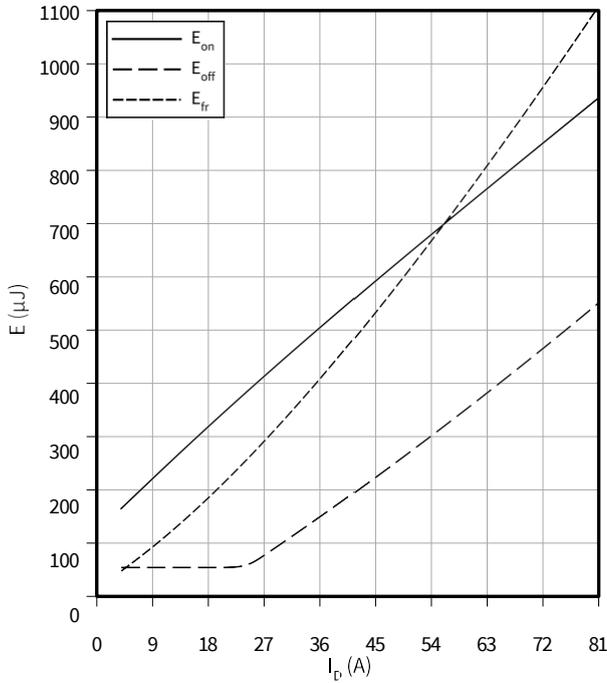


4 特性图

Typical switching energy as a function of drain current, test circuit in Fig. F, 2nd device own body diode: $V_{GS} = 0\text{ V}$

$E = f(I_D)$

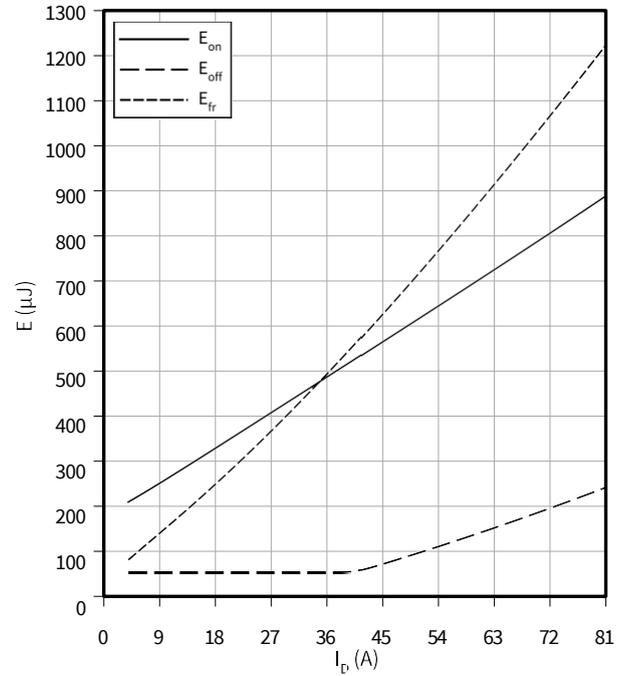
$V_{GS} = 0/18\text{ V}$, $T_{vj} = 175\text{ }^\circ\text{C}$, $R_{G,ext} = 2.3\text{ }\Omega$, $V_{DD} = 800\text{ V}$



Typical switching energy as a function of drain current, test circuit in Fig. F, 2nd device own body diode: $V_{GS} = -5\text{ V}$

$E = f(I_D)$

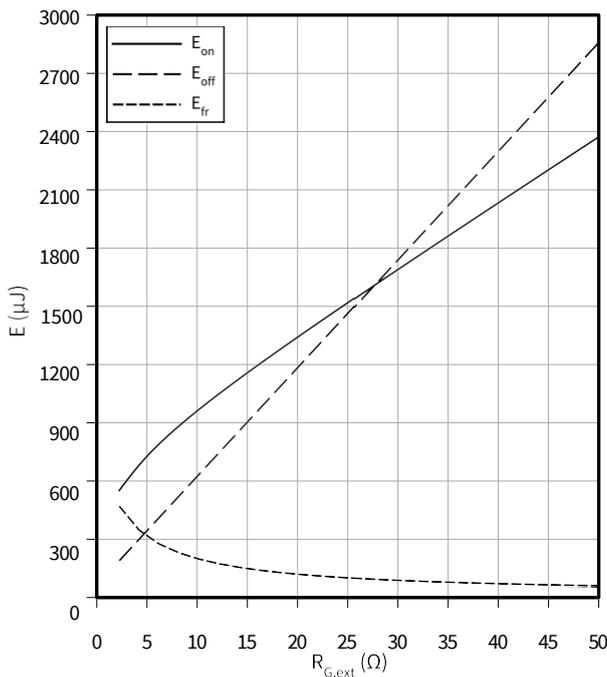
$V_{GS} = -5/18\text{ V}$, $T_{vj} = 175\text{ }^\circ\text{C}$, $R_{G,ext} = 2.3\text{ }\Omega$, $V_{DD} = 800\text{ V}$



Typical switching energy as a function of gate resistance, test circuit in Fig. F, 2nd device own body diode: $V_{GS} = 0\text{ V}$

$E = f(R_{G,ext})$

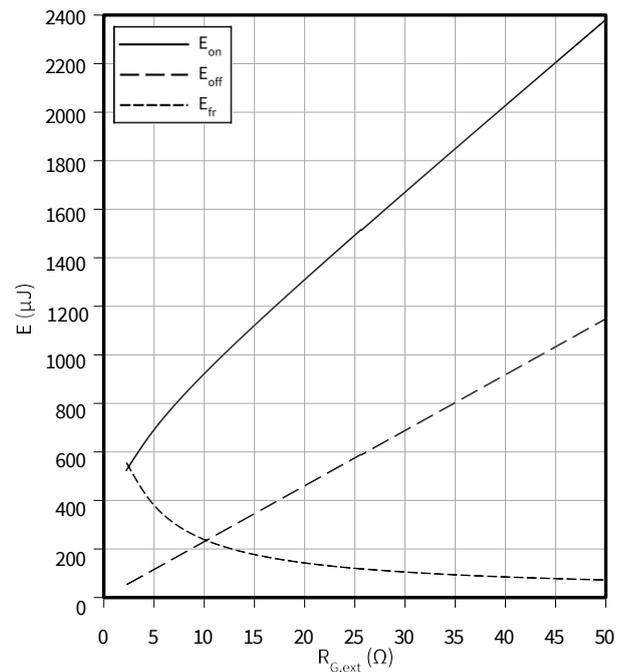
$V_{GS} = 0/18\text{ V}$, $I_D = 40\text{ A}$, $T_{vj} = 175\text{ }^\circ\text{C}$, $V_{DD} = 800\text{ V}$



Typical switching energy as a function of gate resistance, test circuit in Fig. F, 2nd device own body diode: $V_{GS} = -5\text{ V}$

$E = f(R_{G,ext})$

$V_{GS} = -5/18\text{ V}$, $I_D = 40\text{ A}$, $T_{vj} = 175\text{ }^\circ\text{C}$, $V_{DD} = 800\text{ V}$

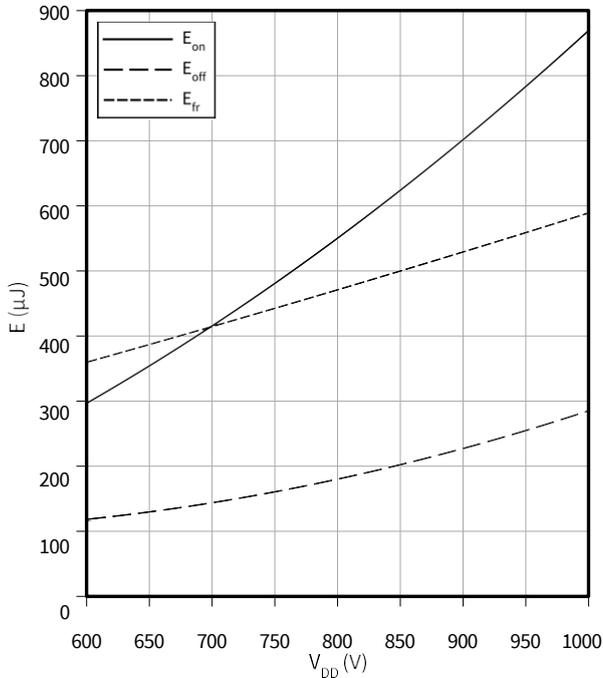


4 特性图

Typical switching energy as a function of DC link voltage, test circuit in Fig. F, 2nd device own body diode: $V_{GS} = 0$ V

$E = f(V_{DD})$

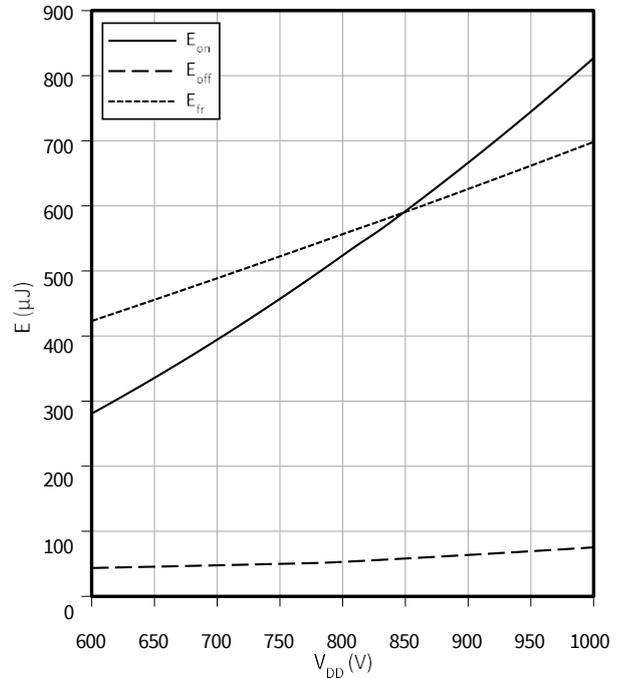
$V_{GS} = 0/18$ V, $I_D = 40$ A, $T_{vj} = 175$ °C, $R_{G,ext} = 2.3$ Ω



Typical switching energy as a function of DC link voltage, test circuit in Fig. F, 2nd device own body diode: $V_{GS} = -5$ V

$E = f(V_{DD})$

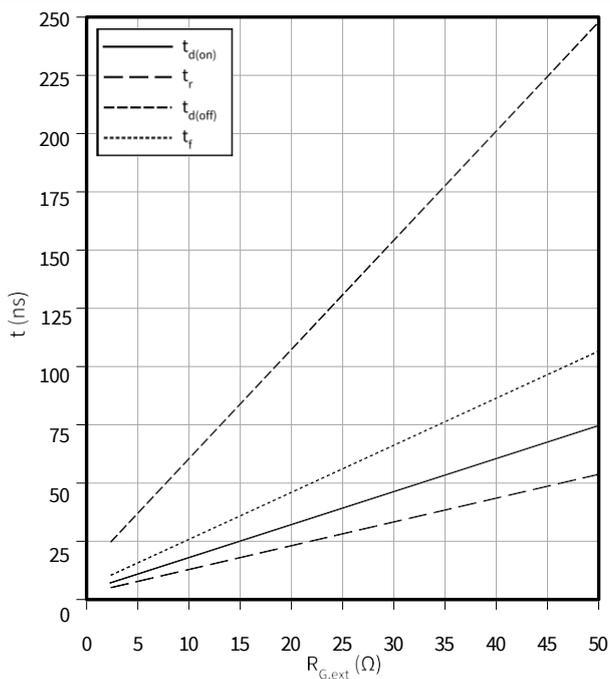
$V_{GS} = -5/18$ V, $I_D = 40$ A, $T_{vj} = 175$ °C, $R_{G,ext} = 2.3$ Ω



Typical switching times as a function of gate resistance, test circuit in Fig. F, 2nd device own body diode: $V_{GS} = 0$ V

$t = f(R_{G,ext})$

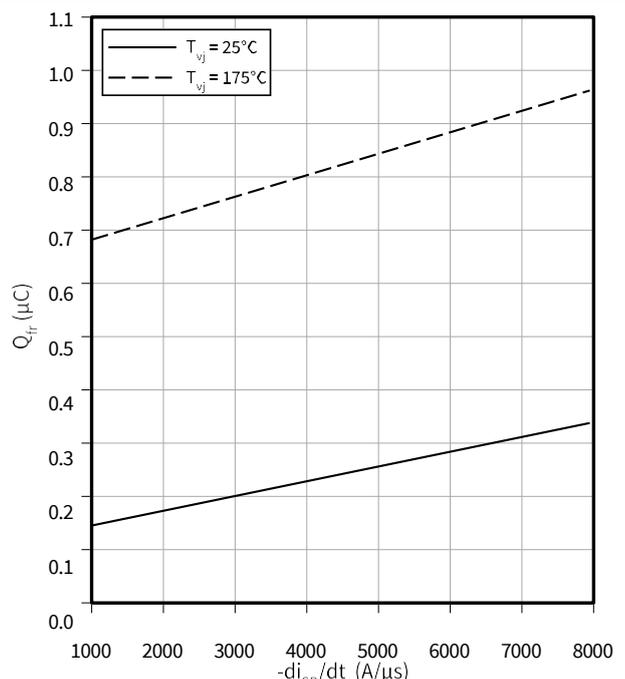
$V_{GS} = 0/18$ V, $I_D = 40$ A, $T_{vj} = 175$ °C, $V_{DD} = 800$ V



Typical reverse recovery charge as a function of reverse drain current slope, test circuit in Fig. F, 2nd device own body diode: $V_{GS} = 0$ V

$Q_{fr} = f(-di_{SD}/dt)$

$V_{GS} = 0/18$ V, $I_{SD} = 40$ A, $V_{DD} = 800$ V

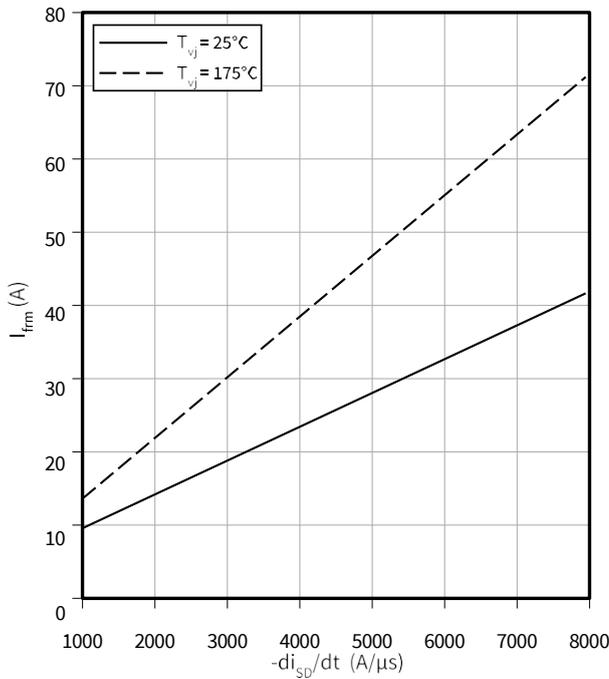


4 特性图

Typical reverse recovery current as a function of reverse drain current slope, test circuit in Fig. F, 2nd device own body diode: $V_{GS} = 0\text{ V}$

$$I_{frm} = f(-di_{SD}/dt)$$

$V_{GS} = 0/18\text{ V}$, $I_{SD} = 40\text{ A}$, $V_{DD} = 800\text{ V}$

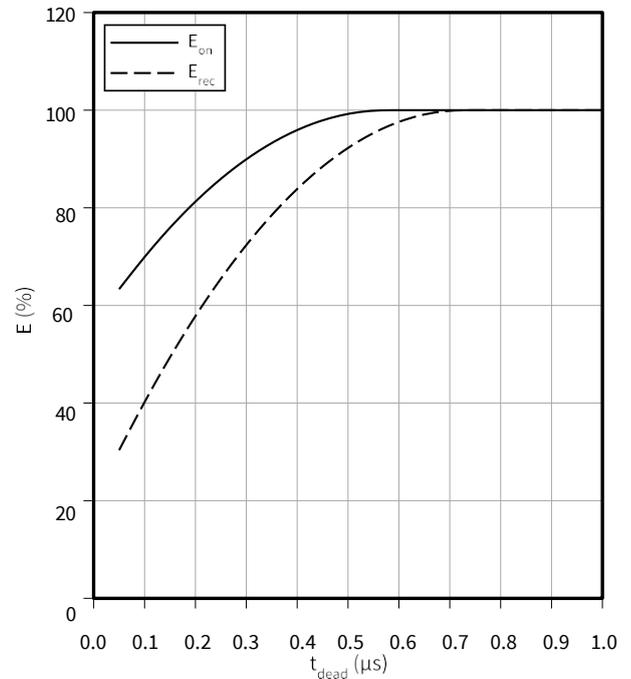


Typical switching energy as a function of dead time / blanking time, test circuit in Fig. F, 2nd device own body diode: $V_{GS} = 0\text{ V}$

$$E = f(t_{dead})$$

$I_D = 40\text{ A}$, $V_{GS} = 0/18\text{ V}$, $T_{vj} = 175\text{ °C}$, $R_{G,ext} = 2.3\text{ }\Omega$

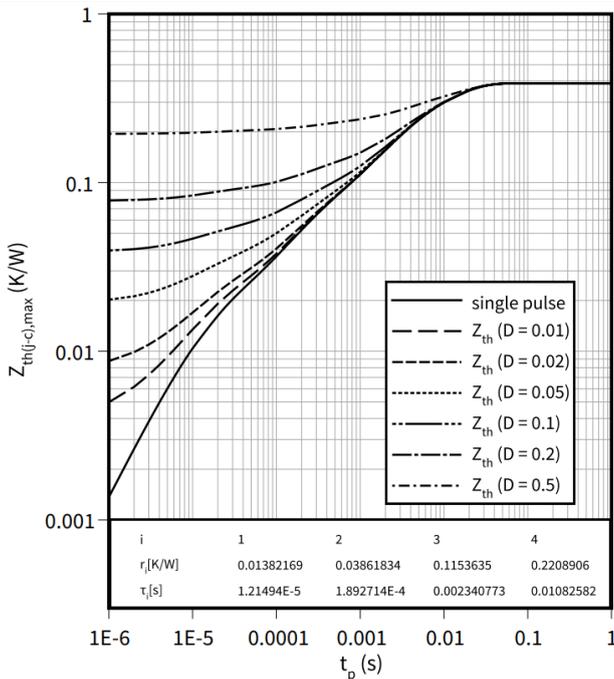
$V_{DD} = 800\text{ V}$



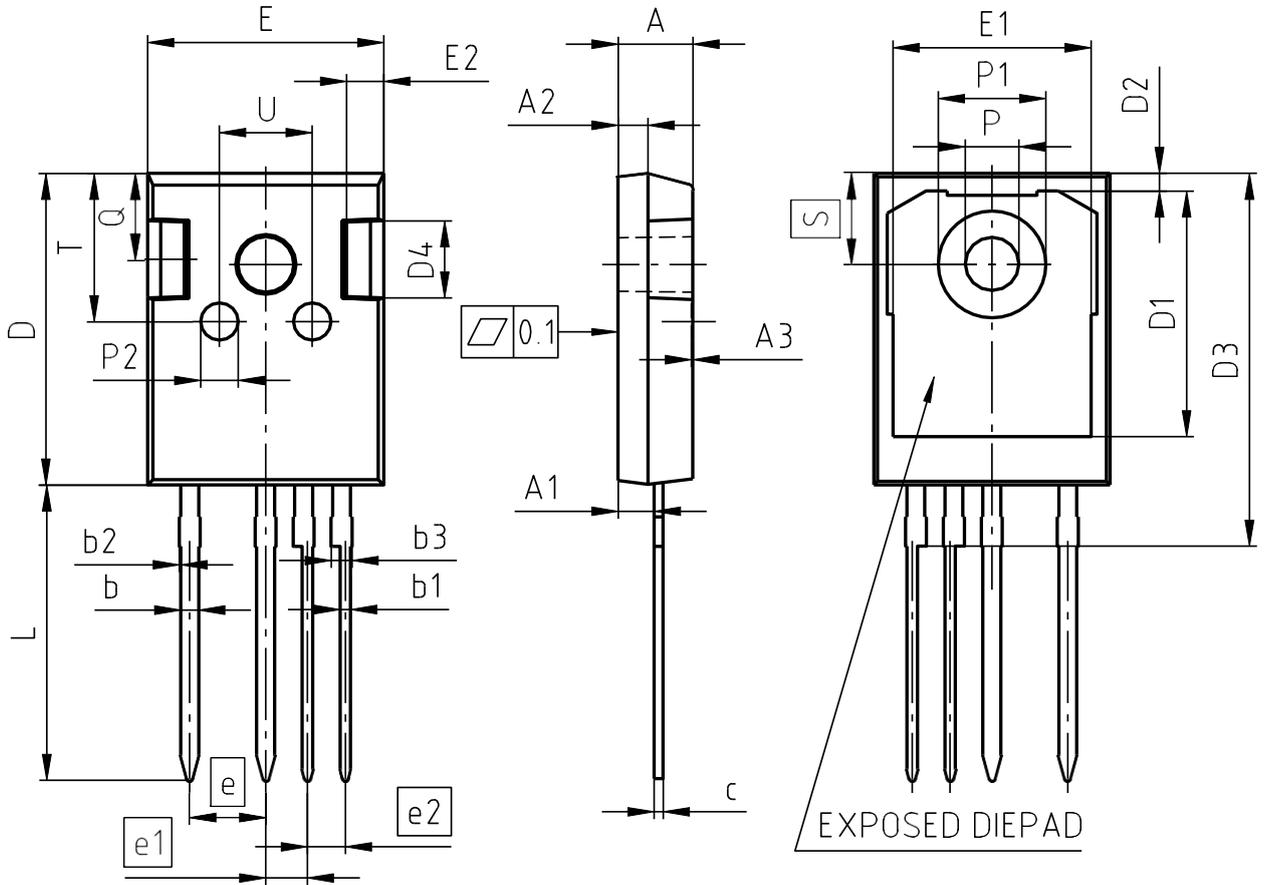
Max. transient thermal impedance (MOSFET/diode)

$$Z_{th(j-c),max} = f(t_p)$$

$$D = t_p/T$$



5 封装外形



NOTES:
ALL DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS.

PACKAGE - GROUP		PG-T0247-4-U02		NUMBER:	
DIMENSIONS	MILLIMETERS		DIMENSIONS	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	4.90	5.10	E	15.70	15.90
A1	2.31	2.51	E1	13.10	13.50
A2	1.90	2.10	E2	2.40	2.60
A3	0.05	0.25	e	5.08	
b	1.10	1.30	e1	2.79	
b1	0.65	0.79	e2	2.54	
b2	---	0.20	N	4	
b3	1.34	1.44	L	19.80	20.10
c	0.58	0.66	øP	3.50	3.70
D	20.90	21.10	øP1	7.00	7.40
D1	16.25	16.85	øP2	2.40	2.60
D2	1.05	1.35	Q	5.60	6.00
D3	24.97	25.27	S	6.15	
D4	4.90	5.10	T	9.80	10.20
			U	6.00	6.40

图 1

6 测试条件

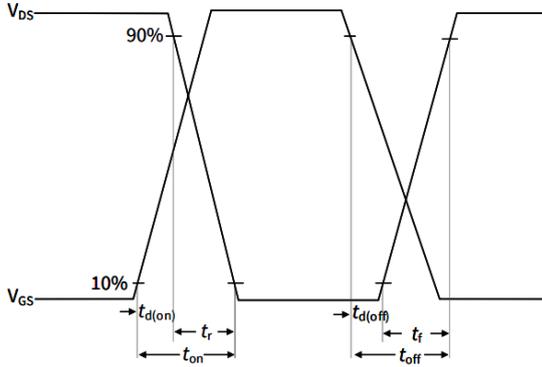


Figure A. Definition of switching times

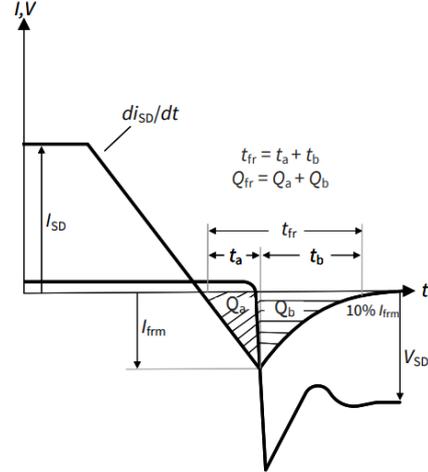


Figure B. Definition of body diode switching characteristics

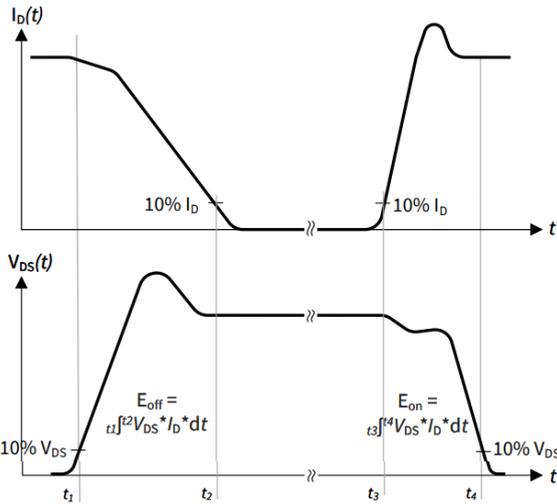


Figure C. Definition of switching losses

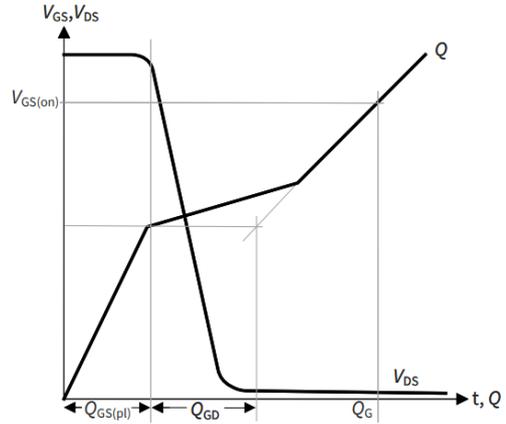


Figure D. Definition of QGD

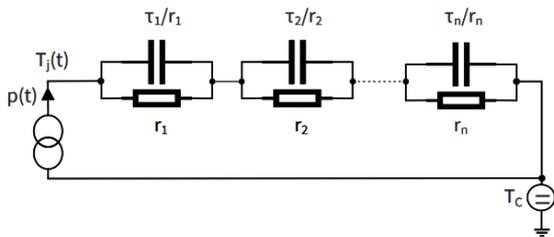


Figure E. Thermal equivalent circuit

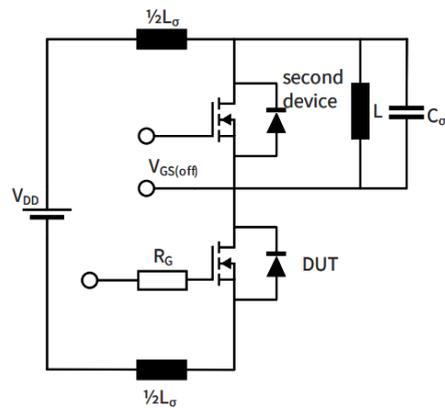


Figure F. Dynamic test circuit
Parasitic inductance L_σ ,
Parasitic capacitor C_σ ,

修订记录

修订记录

Document revision	Date of release	Description of changes
0.10	2025-03-24	Preliminary datasheet
1.00	2025-03-25	Final datasheet
1.10	2025-07-04	Increased I_{DM} in Table 2 Added switching information for $V_{GS} = -5/18\text{ V}$ in Table 5 and 6 and corresponding diagrams Added I_{SDC} in Table 5 Added SOA diagram on page 8 Added diagram $E = f(V_{DD}) @ V_{GS} = 0/18\text{ V}$ Added diagram $E = f(V_{DD}) @ V_{GS} = -5/18\text{ V}$ Editorial changes



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版本 2025-12-24

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